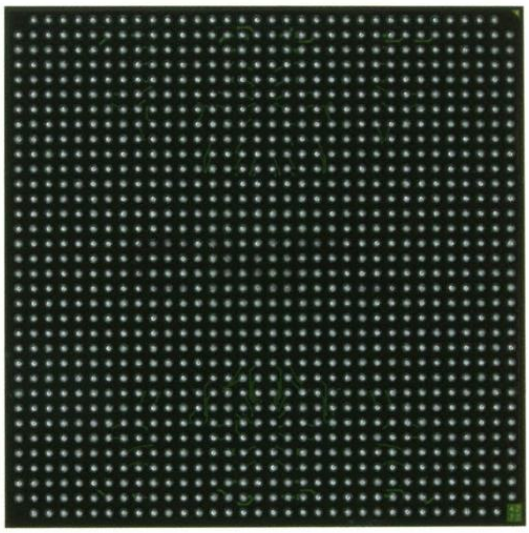

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	3424
Number of Logic Elements/Cells	30816
Total RAM Bits	2506752
Number of I/O	644
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp30-7ffg1152c

Disparity Control

The 8B/10B encoder is initialized with a negative running disparity. Unique control allows forcing the current running disparity state.

TXRUNDISP signals its current running disparity. This may be useful in those cases where there is a need to manipulate the initial running disparity value.

Bits TXCHARDISPMODE and TXCHARDISPVAL control the generation of running disparity before each byte.

For example, the transceiver can generate the sequence

```
K28.5+ K28.5+ K28.5- K28.5-
```

or

```
K28.5- K28.5- K28.5+ K28.5+
```

by specifying inverted running disparity for the second and fourth bytes.

Transmit FIFO

Proper operation of the circuit is only possible if the FPGA clock (TXUSRCLK) is frequency-locked to the reference clock (REFCLK). Phase variations up to one clock cycle are allowable. The FIFO has a depth of four. Overflow or underflow conditions are detected and signaled at the interface. Bypassing of this FIFO is programmable.

8B/10B Encoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

A bypassable 8B/10B encoder is included. The encoder uses the same 256 data characters and 12 control characters used by Gigabit Ethernet, Fibre Channel, and InfiniBand.

The encoder accepts 8 bits of data along with a K-character signal for a total of 9 bits per character applied, and generates a 10 bit character for transmission. If the K-character signal is High, the data is encoded into one of the twelve possible K-characters available in the 8B/10B code. If the K-character input is Low, the 8 bits are encoded as standard data. If the K-character input is High, and a user applies other than one of the twelve possible combinations, TXKERR indicates the error.

8B/10B Decoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

An optional 8B/10B decoder is included. A programmable option allows the decoder to be bypassed. When the 8B/10B decoder is bypassed, the 10-bit character order is, for example,

RXCHARISK[0] (first bit received)
RXRUNDISP[0]
RXDATA[7:0] (last bit received is RXDATA[0])

The decoder uses the same table that is used for Gigabit Ethernet, Fibre Channel, and InfiniBand. In addition to decoding all data and K-characters, the decoder has several extra features. The decoder separately detects both “disparity errors” and “out-of-band” errors. A disparity error is the reception of 10-bit character that exists within the 8B/10B table but has an incorrect disparity. An out-of-band error is the reception of a 10-bit character that does not exist within the 8B/10B table. It is possible to obtain an out-of-band error without having a disparity error. The proper disparity is always computed for both legal and illegal characters. The current running disparity is available at the RXRUNDISP signal.

The 8B/10B decoder performs a unique operation if out-of-band data is detected. If out-of-band data is detected, the decoder signals the error and passes the illegal 10-bits through and places them on the outputs. This can be used for debugging purposes if desired.

The decoder also signals the reception of one of the 12 valid K-characters. In addition, a programmable comma detect is included. The comma detect signal registers a comma on the receipt of any comma+, comma–, or both. Since the comma is defined as a 7-bit character, this includes several out-of-band characters. Another option allows the decoder to detect only the three defined commas (K28.1, K28.5, and K28.7) as comma+, comma–, or both. In total, there are six possible options, three for valid commas and three for "any comma."

Note that all bytes (1, 2, 4, or 8) at the RX FPGA interface each have their own individual 8B/10B indicators (K-character, disparity error, out-of-band error, current running disparity, and comma detect).

Receiver Buffer

The receiver includes buffers (FIFOs) in the datapath. This section gives the reasons for including the buffers and outlines their operation.

The receiver buffer is required for two reasons:

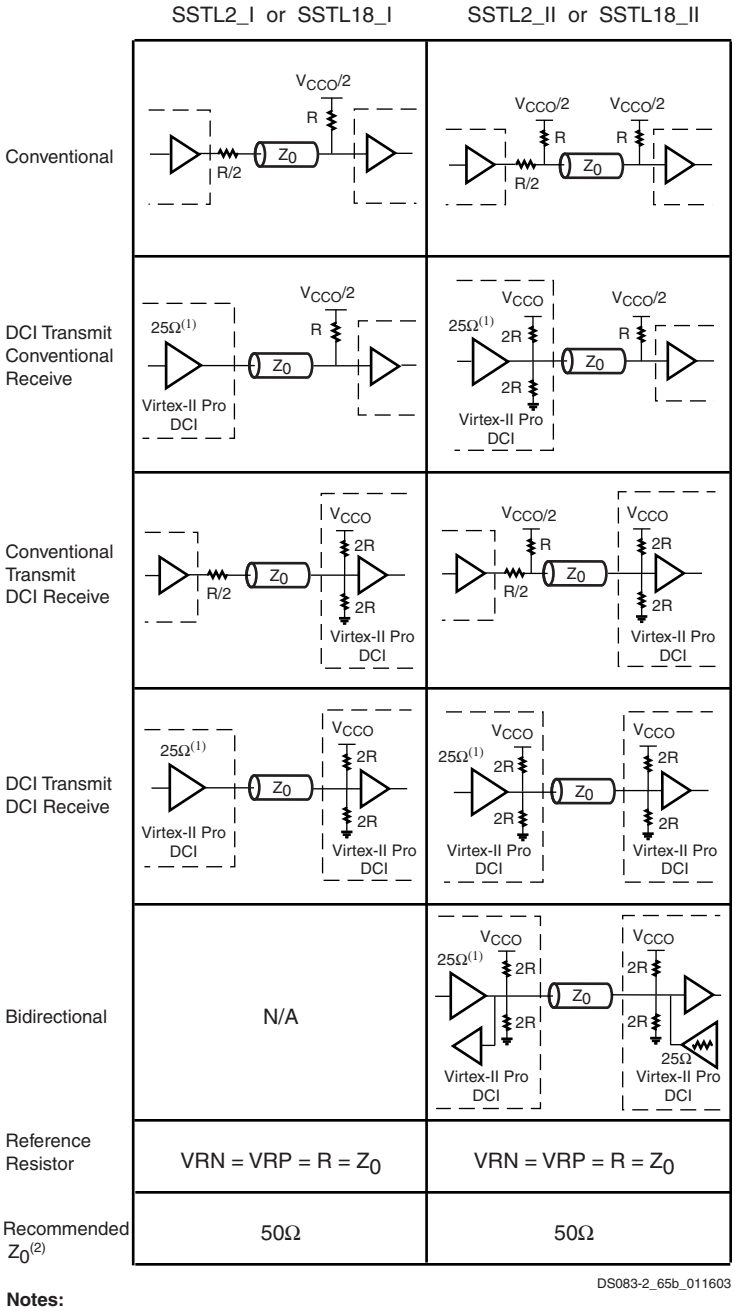
- *Clock correction* to accommodate the slight difference in frequency between the recovered clock RXRECCLK and the internal FPGA user clock RXUSRCLK
- *Channel bonding* to allow realignment of the input stream to ensure proper alignment of data being read through multiple transceivers

The receiver uses an *elastic buffer*, where "elastic" refers to the ability to modify the read pointer for clock correction and channel bonding.

Comma Detection

Word alignment is dependent on the state of comma detect bits. If comma detect is enabled, the transceiver recognizes up to two 10-bit preprogrammed characters. Upon detection of the character or characters, the comma detect output is driven high and the data is synchronously aligned. If a comma is detected and the data is aligned, no further alignment alteration takes place. If a comma is received and realignment is necessary, the data is realigned and an indi-

Figure 29 provides examples illustrating the use of the SSTL2_I_DCI, SSTL2_II_DCI, SSTL18_I_DCI, and SSTL18_II_DCI I/O standards. For a complete list, see the ***Virtex-II Pro Platform FPGA User Guide***.



Notes:
1. The SSTL-compatible 25Ω series resistor is accounted for in the DCI buffer, and it is not DCI controlled.
2. Z_0 is the recommended PCB trace impedance.

Figure 29: **SSTL DCI Usage Examples**

Sum of Products

Each Virtex-II Pro slice has a dedicated OR gate named ORCY, ORing together outputs from the slices carryout and the ORCY from an adjacent slice. The ORCY gate with the dedicated Sum of Products (SOP) chain are designed for implementing large, flexible SOP chains. One input of each ORCY is connected through the fast SOP chain to the output of the previous ORCY in the same slice row. The second input is connected to the output of the top MUXCY in the same slice, as shown in Figure 43.

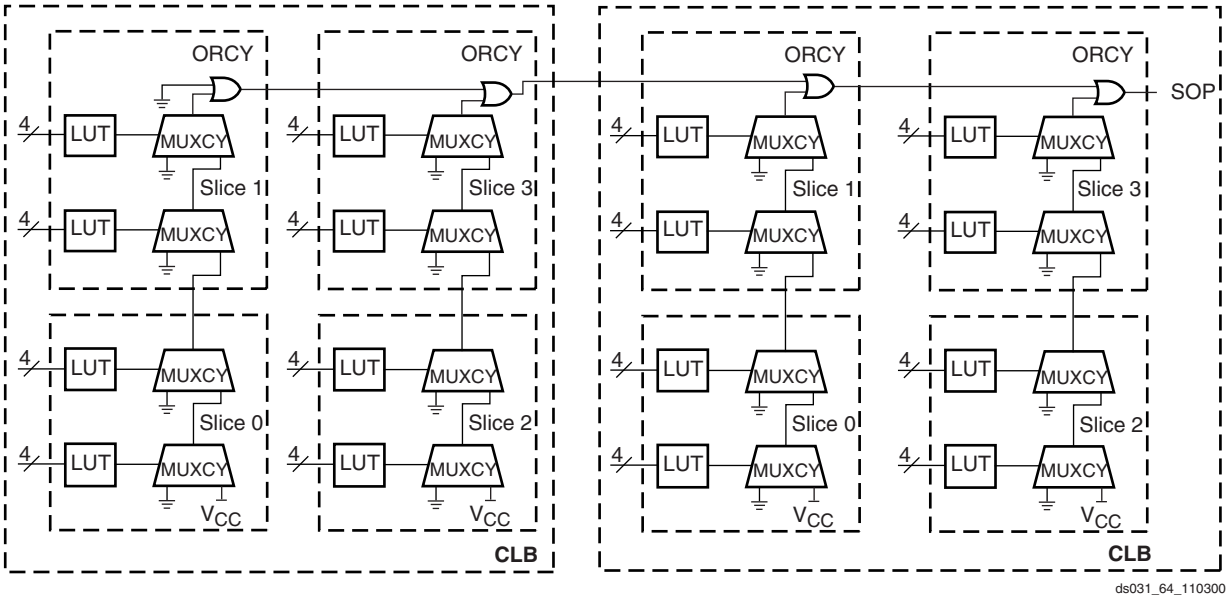


Figure 43: **Horizontal Cascade Chain**

LUTs and MUXCYs can implement large AND gates or other combinatorial logic functions. Figure 44 illustrates LUT and MUXCY resources configured as a 16-input AND gate.

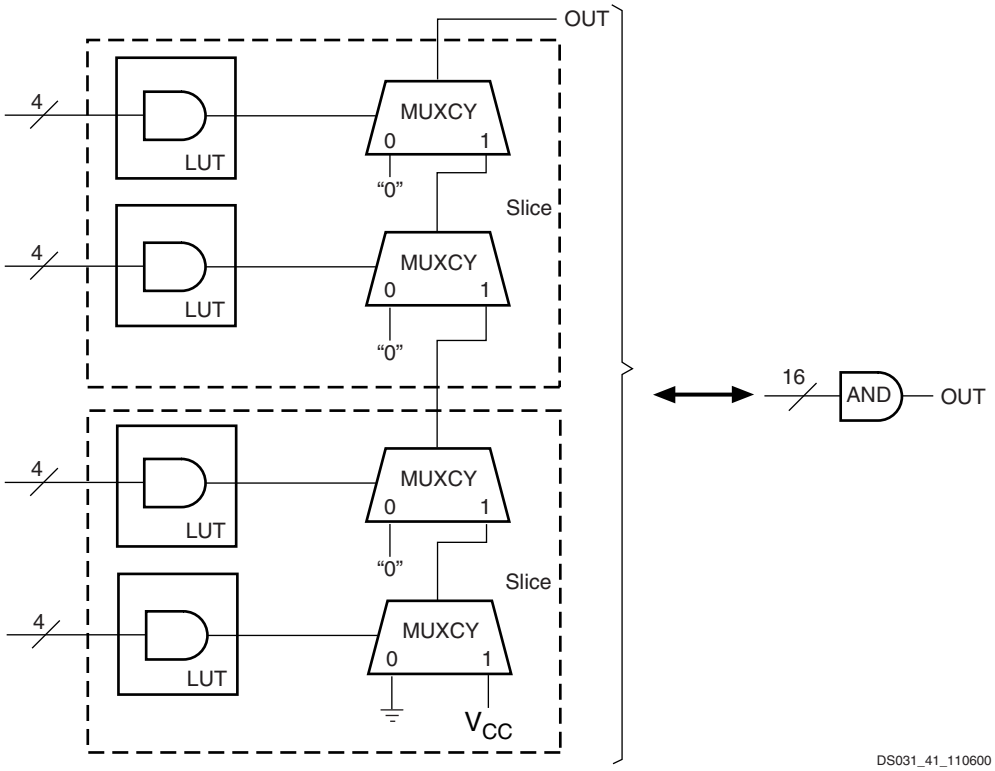


Figure 44: **Wide-Input AND Gate (16 Inputs)**

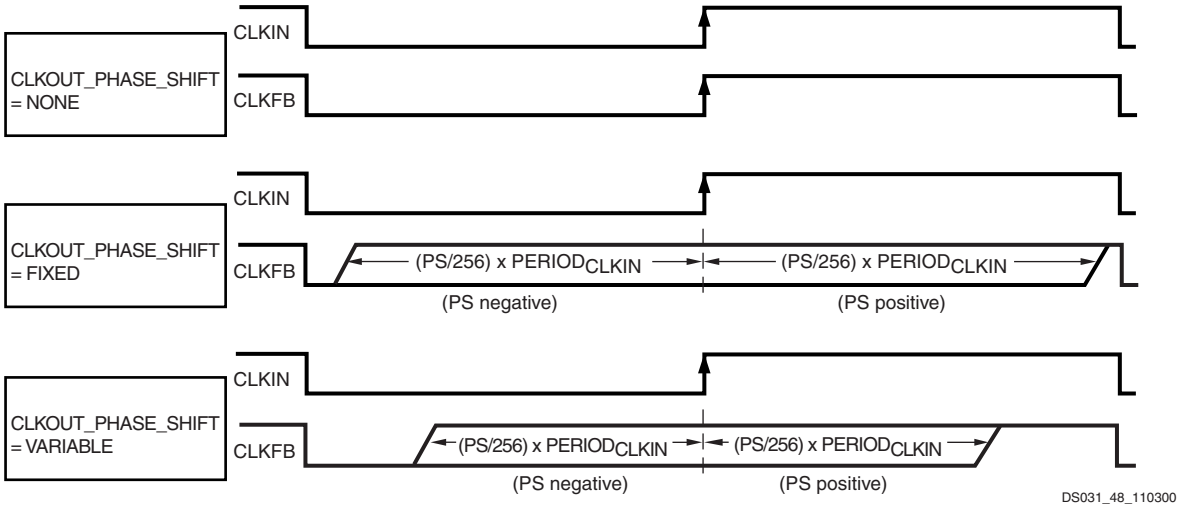


Figure 63: **Fine-Phase Shifting Effects**

Two separate components of the phase shift range must be understood:

- PHASE_SHIFT attribute range
- FINE_SHIFT_RANGE DCM timing parameter range

The PHASE_SHIFT attribute is the numerator in the following equation:

$$\text{Phase Shift (ns)} = (\text{PHASE\_SHIFT}/256) * \text{PERIOD}_{\text{CLKIN}}$$

The full range of this attribute is always -255 to +255, but its practical range varies with CLKIN frequency, as constrained by the FINE_SHIFT_RANGE component, which represents the total delay achievable by the phase shift delay line. Total delay is a function of the number of delay taps used in the circuit. Across process, voltage, and temperature, this absolute range is guaranteed to be as specified under **DCM Timing Parameters** in Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics.

Absolute range (fixed mode) = ± FINE_SHIFT_RANGE

Absolute range (variable mode) = ± FINE_SHIFT_RANGE/2

The reason for the difference between fixed and variable modes is as follows. For variable mode to allow symmetric, dynamic sweeps from -255/256 to +255/256, the DCM sets the "zero phase skew" point as the middle of the delay line, thus dividing the total delay line range in half. In fixed mode, since the PHASE_SHIFT value never changes after configuration, the entire delay line is available for insertion into either the CLKIN or CLKFB path (to create either positive or negative skew).

Taking both of these components into consideration, the following are some usage examples:

- If $\text{PERIOD}_{\text{CLKIN}} = 2 * \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 128, and in variable mode it is limited to ± 64.
- If $\text{PERIOD}_{\text{CLKIN}} = \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 255, and in variable mode it is limited to ± 128.
- If $\text{PERIOD}_{\text{CLKIN}} \leq 0.5 * \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT is limited to ± 255 in either mode.

Operating Modes

The frequency ranges of DCM input and output clocks depend on the operating mode specified, either low-frequency mode or high-frequency mode, according to Table 30. For actual values, see Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics. The CLK2X, CLK2X180, CLK90, and CLK270 outputs are not available in high-frequency mode.

High or low-frequency mode is selected by an attribute.

Table 30: **DCM Frequency Ranges**

Output Clock	Low-Frequency Mode		High-Frequency Mode	
	CLKIN Input	CLK Output	CLKIN Input	CLK Output
CLK0, CLK180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_1X_HF
CLK90, CLK270	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	NA	NA
CLK2X, CLK2X180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_2X_LF	NA	NA
CLKDV	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_DV_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_DV_HF
CLKFX, CLKFX180	CLKIN_FREQ_FX_LF	CLKOUT_FREQ_FX_LF	CLKIN_FREQ_FX_HF	CLKOUT_FREQ_FX_HF

Master SelectMAP Mode

This mode is a master version of the SelectMAP mode. The device is configured byte-wide on a CCLK supplied by the Virtex-II Pro FPGA device. Timing is similar to the Slave SerialMAP mode except that CCLK is supplied by the Virtex-II Pro FPGA.

Boundary-Scan (JTAG, IEEE 1532) Mode

In Boundary-Scan mode, dedicated pins are used for configuring the Virtex-II Pro device. The configuration is done entirely through the IEEE 1149.1 Test Access Port (TAP). Virtex-II Pro device configuration using Boundary-Scan is compatible with with IEEE 1149.1-1993 standard and the new IEEE 1532 standard for In-System Configurable (ISC) devices. The IEEE 1532 standard is backward compliant with the IEEE 1149.1-1993 TAP and state machine. The IEEE Standard 1532 for In-System Configurable (ISC) devices is intended to be programmed, reprogrammed, or tested on the board via a physical and logical protocol. Configuration through the Boundary-Scan port is always available, independent of the mode selection. Selecting the Boundary-Scan mode simply turns off the other modes.

Table 32: **Virtex-II Pro Configuration Mode Pin Settings**

Configuration Mode(1)	M2	M1	M0	CCLK Direction	Data Width	Serial D_{OUT}(2)
Master Serial	0	0	0	Out	1	Yes
Slave Serial	1	1	1	In	1	Yes
Master SelectMAP	0	1	1	Out	8	No
Slave SelectMAP	1	1	0	In	8	No
Boundary-Scan	1	0	1	N/A	1	No

Notes:
1. The HSWAP_EN pin controls the pull-ups. Setting M2, M1, and M0 selects the configuration mode, while the HSWAP_EN pin controls whether or not the pull-ups are used.
2. Daisy chaining is possible only in modes where Serial D_{OUT} is used. For example, in SelectMAP modes, the first device does NOT support daisy chaining of downstream devices.

Table 33 lists the default total number of bits required to configure each device.

Table 33: **Virtex-II Pro Default Bitstream Lengths**

Device	Number of Configuration Bits
XC2VP2	1,305,376
XC2VP4	3,006,496
XC2VP7	4,485,408
XC2VP20	8,214,560
XC2VPX20	8,214,560
XC2VP30	11,589,920
XC2VP40	15,868,192
XC2VP50	19,021,344
XC2VP70	26,098,976
XC2VPX70	26,098,976
XC2VP100	34,292,768

Configuration Sequence

The configuration of Virtex-II Pro devices is a three-phase process. First, the configuration memory is cleared. Next, configuration data is loaded into the memory, and finally, the logic is activated by a start-up process.

Configuration is automatically initiated on power-up unless it is delayed by the user. The INIT_B pin can be held Low using an open-drain driver. An open-drain is required since INIT_B is a bidirectional open-drain pin that is held Low by a Virtex-II Pro FPGA device while the configuration memory is being cleared. Extending the time that the pin is Low causes the configuration sequencer to wait. Thus, configuration is delayed by preventing entry into the phase where data is loaded.

The configuration process can also be initiated by asserting the PROG_B pin. The end of the memory-clearing phase is signaled by the INIT_B pin going High, and the completion of the entire process is signaled by the DONE pin going High. The Global Set/Reset (GSR) signal is pulsed after the last frame of configuration data is written but before the start-up sequence. The GSR signal resets all flip-flops on the device.

The default start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary. One CCLK cycle later, the Global Write Enable (GWE) signal is released. This permits the internal storage elements to begin changing state in response to the logic and the user clock.

The relative timing of these events can be changed via configuration options in software. In addition, the GTS and GWE events can be made dependent on the DONE pins of multiple devices all going High, forcing the devices to start

Date	Version	Revision
10/10/05	4.5	• Changed XC2VPX70 variable baud rate specification to fixed-rate operation at 4.25 Gb/s.
03/05/07	4.6	*No changes in Module 2 for this revision.*
11/05/07	4.7	• Updated copyright notice and legal disclaimer. • Debug Interface, page 19, and Boundary-Scan (JTAG, IEEE 1532) Mode, page 57: Updated IEEE 1149.1 compliance statement.
06/21/11	5.0	Added *Product Not Recommended for New Designs* banner.

Notice of Disclaimer

Virtex-II Pro Data Sheet

The Virtex-II Pro Data Sheet contains the following modules:

- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview (Module 1)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description (Module 2)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics (Module 3)
- Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Pinout Information (Module 4)

Table 32: **RocketIO RXUSRCLK2 Switching Characteristics *(Continued)***

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
RXBUFSTATUS status outputs	$T_{GCKST_}$RBSTA	0.45	0.45	0.50	ns, max
RXCHECKINGCRC status output	$T_{GCKST_}$RCCRC	0.36	0.40	0.44	ns, max
RXCRCERR status output	$T_{GCKST_}$RCRCE	0.36	0.40	0.44	ns, max
CHBONDDONE status output	$T_{GCKST_}$CHBD	0.50	0.50	0.55	ns, max
RXCHARISK status outputs	$T_{GCKST_}$RKCH	0.50	0.50	0.55	ns, max
RXRUNDISP status outputs	$T_{GCKST_}$RRDIS	0.50	0.50	0.55	ns, max
RXDATA data outputs	$T_{GCKDO_}$RDAT	0.50	0.50	0.55	ns, max
Clock					
RXUSRCLK2 minimum pulse width, High	$T_{GPWH_}$RX2	1.42	1.42	2.25	ns, min
RXUSRCLK2 minimum pulse width, Low	$T_{GPWL_}$RX2	1.42	1.42	2.25	ns, min

Table 33: **RocketIO X TXUSRCLK2 Switching Characteristics**

		Speed Grade			
Description	**Symbol**	**-7**	**-6**	**-5**	**Units**
Setup and Hold Relative to Clock (TXUSRCLK2)					
TXBYPASS8B10B control inputs	$T_{GCCK_}$TBYP/$T_{GCKC_}$TBYP				ns, min
TXPOLARITY control input	$T_{GCCK_}$TPOL/$T_{GCKC_}$TPOL				ns, min
TXINHIBIT control inputs	$T_{GCCK_}$TINH/$T_{GCKC_}$TINH				ns, min
LOOPBACK control inputs	$T_{GCCK_}$LBK/$T_{GCKC_}$LBK				ns, min
TXRESET control input	$T_{GCCK_}$TRST/$T_{GCKC_}$TRST				ns, min
TXCHARISK control inputs	$T_{GCCK_}$TKCH/$T_{GCKC_}$TKCH				ns, min
TXCHARDISPMODE control inputs	$T_{GCCK_}$TCDM/$T_{GCKC_}$TCDM				ns, min
TXCHARDISPVAL control inputs	$T_{GCCK_}$TCDV/$T_{GCKC_}$TCDV				ns, min
TXDATAWIDTH control inputs	$T_{GCCK_}$TDATW/$T_{GCCK_}$TDATW				ns, min
TXENC64B66BUSE TXENC8B10BUSE control inputs	$T_{GCCK_}$TENC/$T_{GCCK_}$TENC				ns, min
TXINTDATAWIDTH control inputs	$T_{GCCK_}$TIDATW/$T_{GCCK_}$TIDATW				ns, min
TXGEARBOX64B66BUSE control inputs	$T_{GCCK_}$TXGEAR/$T_{GCCK_}$TXGEAR				ns, min
TXSCRAM64B66BUSE control inputs	$T_{GCCK_}$TXSCBL/$T_{GCCK_}$TXSCBL				ns, min
REFCLKSEL REFCLKBSEL control inputs	$T_{GCCK_}$RFCKSL/$T_{GCCK_}$RFCKSL				ns, min
TXDATA data inputs	$T_{GDCK_}$TDAT/$T_{GCKD_}$TDAT				ns, min
Clock to Out					
TXBUFERR status output	$T_{GCKST_}$TBERR				ns, max
TXKERR status outputs	$T_{GCKST_}$TKERR				ns, max
TXRUNDISP status outputs	$T_{GCKST_}$TRDIS				ns, max
Clock					
TXUSRCLK2 minimum pulse width, High	$T_{GPWH_}$TX2				ns, min
TXUSRCLK2 minimum pulse width, Low	$T_{GPWL_}$TX2				ns, min

Table 35: **IOB Input Switching Characteristics *(Continued)***

			Speed Grade			
Description	**Symbol**	**Device**	**-7**	**-6**	**-5**	**Units**
Setup and Hold Times With Respect to Clock at IOB Input Register						
Pad, no delay	T_{IOPICK}/T_{IOICKP}	All	0.84/–0.61	0.86/–0.63	0.90/–0.67	ns, min
Pad, with delay	$T_{IOPICKD}/T_{IOICKPD}$	XC2VP2	2.28/–1.89	2.60/–2.15	2.95/–2.43	ns, max
		XC2VP4	2.55/–2.10	2.87/–2.36	3.21/–2.65	ns, max
		XC2VP7	2.48/–2.05	2.82/–2.32	3.15/–2.60	ns, max
		XC2VP20	2.63/–2.05	3.02/–2.35	3.40/–2.66	ns, max
		XC2VPX20	2.63/–2.05	3.02/–2.35	3.40/–2.66	ns, max
		XC2VP30	2.67/–2.07	3.09/–2.42	3.49/–2.73	ns, max
		XC2VP40	3.28/–2.56	3.61/–2.83	4.01/–3.15	ns, max
		XC2VP50	3.84/–3.02	4.08/–3.21	4.42/–3.48	ns, max
		XC2VP70	3.98/–3.13	4.23/–3.33	4.55/–3.58	ns, max
		XC2VPX70	3.98/–3.13	4.23/–3.33	4.55/–3.58	ns, max
		XC2VP100	N/A	6.48/–5.13	7.04/–5.57	ns, max
ICE input	$T_{IOICECK}/T_{IOCKICE}$	All	0.39/ 0.01	0.44/ 0.01	0.49/ 0.01	ns, min
SR input (IFF, synchronous)	$T_{IOSRCKI}$	All	0.52	0.57	0.75	ns, min
Set/Reset Delays						
SR input to IQ (asynchronous)	T_{IOSRIQ}	All	1.13	1.27	1.42	ns, max
GSR to output IQ	T_{GSRQ}	All	5.87	6.75	7.43	ns, max

Notes:
1. Input timing for LVCMOS25 is measured at 1.25V. For other I/O standards, see Table 39.

Table 38: **IOB Output Switching Characteristics Standard Adjustments *(Continued)***

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
LVCMOS, 2.5V, Fast, 6 mA	LVCMOS25_F6	$T_{OLVCMOS25\_F6}$	0.62	0.71	0.78	ns
LVCMOS, 2.5V, Fast, 8 mA	LVCMOS25_F8	$T_{OLVCMOS25\_F8}$	0.20	0.23	0.25	ns
LVCMOS, 2.5V, Fast, 12 mA	LVCMOS25_F12	$T_{OLVCMOS25\_F12}$	0.00	0.00	0.00	ns
LVCMOS, 2.5V, Fast, 16 mA	LVCMOS25_F16	$T_{OLVCMOS25\_F16}$	–0.03	–0.03	–0.04	ns
LVCMOS, 2.5V, Fast, 24 mA	LVCMOS25_F24	$T_{OLVCMOS25\_F24}$	–0.15	–0.15	–0.15	ns
LVCMOS, 1.8V, Slow, 2 mA	LVCMOS18_S2	$T_{OLVCMOS18\_S2}$	4.20	4.83	5.31	ns
LVCMOS, 1.8V, Slow, 4 mA	LVCMOS18_S4	$T_{OLVCMOS18\_S4}$	2.76	3.18	3.49	ns
LVCMOS, 1.8V, Slow, 6 mA	LVCMOS18_S6	$T_{OLVCMOS18\_S6}$	1.91	2.20	2.41	ns
LVCMOS, 1.8V, Slow, 8 mA	LVCMOS18_S8	$T_{OLVCMOS18\_S8}$	1.92	2.20	2.42	ns
LVCMOS, 1.8V, Slow, 12 mA	LVCMOS18_S12	$T_{OLVCMOS18\_S12}$	1.58	1.81	1.99	ns
LVCMOS, 1.8V, Slow, 16 mA	LVCMOS18_S16	$T_{OLVCMOS18\_S16}$	0.76	0.87	0.96	ns
LVCMOS, 1.8V, Fast, 2 mA	LVCMOS18_F2	$T_{OLVCMOS18\_F2}$	2.34	2.69	2.95	ns
LVCMOS, 1.8V, Fast, 4 mA	LVCMOS18_F4	$T_{OLVCMOS18\_F4}$	0.71	0.81	0.89	ns
LVCMOS, 1.8V, Fast, 6 mA	LVCMOS18_F6	$T_{OLVCMOS18\_F6}$	0.50	0.57	0.63	ns
LVCMOS, 1.8V, Fast, 8 mA	LVCMOS18_F8	$T_{OLVCMOS18\_F8}$	0.48	0.55	0.61	ns
LVCMOS, 1.8V, Fast, 12 mA	LVCMOS18_F12	$T_{OLVCMOS18\_F12}$	0.30	0.34	0.38	ns
LVCMOS, 1.8V, Fast, 16 mA	LVCMOS18_F16	$T_{OLVCMOS18\_F16}$	0.11	0.12	0.13	ns
LVCMOS, 1.5V, Slow, 2 mA	LVCMOS15_S2	$T_{OLVCMOS15\_S2}$	6.19	7.12	7.83	ns
LVCMOS, 1.5V, Slow, 4 mA	LVCMOS15_S4	$T_{OLVCMOS15\_S4}$	4.28	4.93	5.42	ns
LVCMOS, 1.5V, Slow, 6 mA	LVCMOS15_S6	$T_{OLVCMOS15\_S6}$	2.81	3.24	3.56	ns
LVCMOS, 1.5V, Slow, 8 mA	LVCMOS15_S8	$T_{OLVCMOS15\_S8}$	2.55	2.93	3.23	ns
LVCMOS, 1.5V, Slow, 12 mA	LVCMOS15_S12	$T_{OLVCMOS15\_S12}$	1.31	1.51	1.66	ns
LVCMOS, 1.5V, Slow, 16 mA	LVCMOS15_S16	$T_{OLVCMOS15\_S16}$	1.28	1.47	1.62	ns
LVCMOS, 1.5V, Fast, 2 mA	LVCMOS15_F2	$T_{OLVCMOS15\_F2}$	2.26	2.60	2.86	ns
LVCMOS, 1.5V, Fast, 4 mA	LVCMOS15_F4	$T_{OLVCMOS15\_F4}$	1.66	1.90	2.09	ns
LVCMOS, 1.5V, Fast, 6 mA	LVCMOS15_F6	$T_{OLVCMOS15\_F6}$	0.65	0.75	0.82	ns
LVCMOS, 1.5V, Fast, 8 mA	LVCMOS15_F8	$T_{OLVCMOS15\_F8}$	0.94	1.08	1.19	ns
LVCMOS, 1.5V, Fast, 12 mA	LVCMOS15_F12	$T_{OLVCMOS15\_F12}$	0.25	0.29	0.32	ns
LVCMOS, 1.5V, Fast, 16 mA	LVCMOS15_F16	$T_{OLVCMOS15\_F16}$	0.28	0.32	0.35	ns
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	T_{OLVDS_25}	0.01	0.01	0.01	ns
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	$T_{OLVDSEXT\_25}$	0.13	0.15	0.16	ns
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	T_{OULVDS_25}	0.13	0.14	0.16	ns
BLVDS (Bus LVDS), 2.5V	BLVDS_25	T_{OBLVDS_25}	0.00	0.00	0.00	ns
LDT (HyperTransport), 2.5V	LDT_25	T_{OLDT_25}	0.13	0.14	0.16	ns
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	$T_{OLVPECL\_25}$	0.17	0.19	0.21	ns
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	T_{OPCI33_3}	0.83	0.93	1.01	ns
PCI, 66 MHz, 3.3V	PCI66_3	T_{OPCI66_3}	0.89	0.97	1.05	ns
PCI-X, 133 MHz, 3.3V	PCIX	T_{OPCIX}	0.92	1.02	1.10	ns
GTL (Gunning Transceiver Logic)	GTL	T_{OGTL}	0.08	0.10	0.11	ns
GTL Plus	GTLP	T_{OGTLP}	0.04	0.05	0.06	ns
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	T_{OHSTL_I}	0.56	0.64	0.70	ns

Table 6: **FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	VCCO_7	K7			
7	VCCO_7	J7			
7	VCCO_7	H6			
7	VCCO_7	G6			
N/A	CCLK	W20			
N/A	PROG_B	B1			
N/A	DONE	Y18			
N/A	M0	Y4			
N/A	M1	W3			
N/A	M2	Y5			
N/A	TCK	B22			
N/A	TDI	D3			
N/A	TDO	D20			
N/A	TMS	A21			
N/A	PWRDWN_B	Y19			
N/A	HSWAP_EN	A2			
N/A	RSVD	C18			
N/A	VBATT	C19			
N/A	DXP	C4			
N/A	DXN	C5			
N/A	AVCCAUXTX4	B4	NC	NC	
N/A	VTTXPAD4	B3	NC	NC	
N/A	TXNPAD4	A3	NC	NC	
N/A	TXPPAD4	A4	NC	NC	
N/A	GNDA4	C6	NC	NC	
N/A	RXPPAD4	A5	NC	NC	
N/A	RXNPAD4	A6	NC	NC	
N/A	VTRXPAD4	B5	NC	NC	
N/A	AVCCAUXRX4	B6	NC	NC	
N/A	AVCCAUXTX6	B8			
N/A	VTTXPAD6	B7			
N/A	TXNPAD6	A7			
N/A	TXPPAD6	A8			
N/A	GNDA6	C9			
N/A	RXPPAD6	A9			
N/A	RXNPAD6	A10			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
7	IO_L52P_7	M7			
7	IO_L52N_7/VREF_7	L7			
7	IO_L50P_7	K1			
7	IO_L50N_7	K2			
7	IO_L49P_7	L3			
7	IO_L49N_7	K3			
7	IO_L48P_7	K4			
7	IO_L48N_7	K5			
7	IO_L46P_7	L8			
7	IO_L46N_7/VREF_7	K8			
7	IO_L44P_7	J1			
7	IO_L44N_7	J2			
7	IO_L43P_7	J3			
7	IO_L43N_7	J4			
7	IO_L42P_7	J5			
7	IO_L42N_7	J6			
7	IO_L40P_7	J7			
7	IO_L40N_7/VREF_7	J8			
7	IO_L38P_7	H1			
7	IO_L38N_7	H2			
7	IO_L37P_7	H6			
7	IO_L37N_7	H7			
7	IO_L36P_7	G1			
7	IO_L36N_7	G2			
7	IO_L34P_7	G3			
7	IO_L34N_7/VREF_7	G4			
7	IO_L32P_7	H5			
7	IO_L32N_7	G5			
7	IO_L31P_7	F1			
7	IO_L31N_7	F2			
7	IO_L24P_7	F3	NC		
7	IO_L24N_7	F4	NC		
7	IO_L06P_7	G6			
7	IO_L06N_7	F6			
7	IO_L04P_7	E1			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	IO_L05_4/No_Pair		AD8			
4	IO_L06N_4/VRP_4		AG8			
4	IO_L06P_4/VRN_4		AH8			
4	IO_L07N_4		AC10			
4	IO_L07P_4/VREF_4		AD10			
4	IO_L08N_4		AE7			
4	IO_L08P_4		AE8			
4	IO_L09N_4		AJ8			
4	IO_L09P_4/VREF_4		AK8			
4	IO_L37N_4		AC11			
4	IO_L37P_4		AD11			
4	IO_L38N_4		AF8			
4	IO_L38P_4		AF9			
4	IO_L39N_4		AF10			
4	IO_L39P_4		AG10			
4	IO_L43N_4		AC12			
4	IO_L43P_4		AD12			
4	IO_L44N_4		AE9			
4	IO_L44P_4		AE10			
4	IO_L45N_4		AH9			
4	IO_L45P_4/VREF_4		AJ9			
4	IO_L46N_4		AC13	NC		
4	IO_L46P_4		AD13	NC		
4	IO_L47N_4		AE11	NC		
4	IO_L47P_4		AE12	NC		
4	IO_L48N_4		AH10	NC		
4	IO_L48P_4		AH11	NC		
4	IO_L49N_4		AB14	NC		
4	IO_L49P_4		AC14	NC		
4	IO_L50_4/No_Pair		AF11	NC		
4	IO_L53_4/No_Pair		AG11	NC		
4	IO_L54N_4		AJ10	NC		
4	IO_L54P_4		AK10	NC		
4	IO_L56N_4		AF12	NC		
4	IO_L56P_4		AF13	NC		
4	IO_L57N_4		AG13	NC		

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
5	IO_L48N_5		AH20	NC		
5	IO_L48P_5		AH21	NC		
5	IO_L47N_5		AE19	NC		
5	IO_L47P_5		AE20	NC		
5	IO_L46N_5		AD18	NC		
5	IO_L46P_5		AC18	NC		
5	IO_L45N_5/VREF_5		AJ22			
5	IO_L45P_5		AH22			
5	IO_L44N_5		AE21			
5	IO_L44P_5		AE22			
5	IO_L43N_5		AD19			
5	IO_L43P_5		AC19			
5	IO_L39N_5		AG21			
5	IO_L39P_5		AF21			
5	IO_L38N_5		AF22			
5	IO_L38P_5		AF23			
5	IO_L37N_5		AD20			
5	IO_L37P_5		AC20			
5	IO_L09N_5/VREF_5		AK23			
5	IO_L09P_5		AJ23			
5	IO_L08N_5		AE23			
5	IO_L08P_5		AE24			
5	IO_L07N_5/VREF_5		AD21			
5	IO_L07P_5		AC21			
5	IO_L06N_5/VRP_5		AH23			
5	IO_L06P_5/VRN_5		AG23			
5	IO_L05_5/No_Pair		AD23			
5	IO_L03N_5/D4		AH24			
5	IO_L03P_5/D5		AG24			
5	IO_L02N_5/D6		AD22			
5	IO_L02P_5/D7		AC22			
5	IO_L01N_5/RDWR_B		AF24			
5	IO_L01P_5/CS_B		AG25			
6	IO_L01P_6/VRN_6		AK28			
6	IO_L01N_6/VRP_6		AJ28			

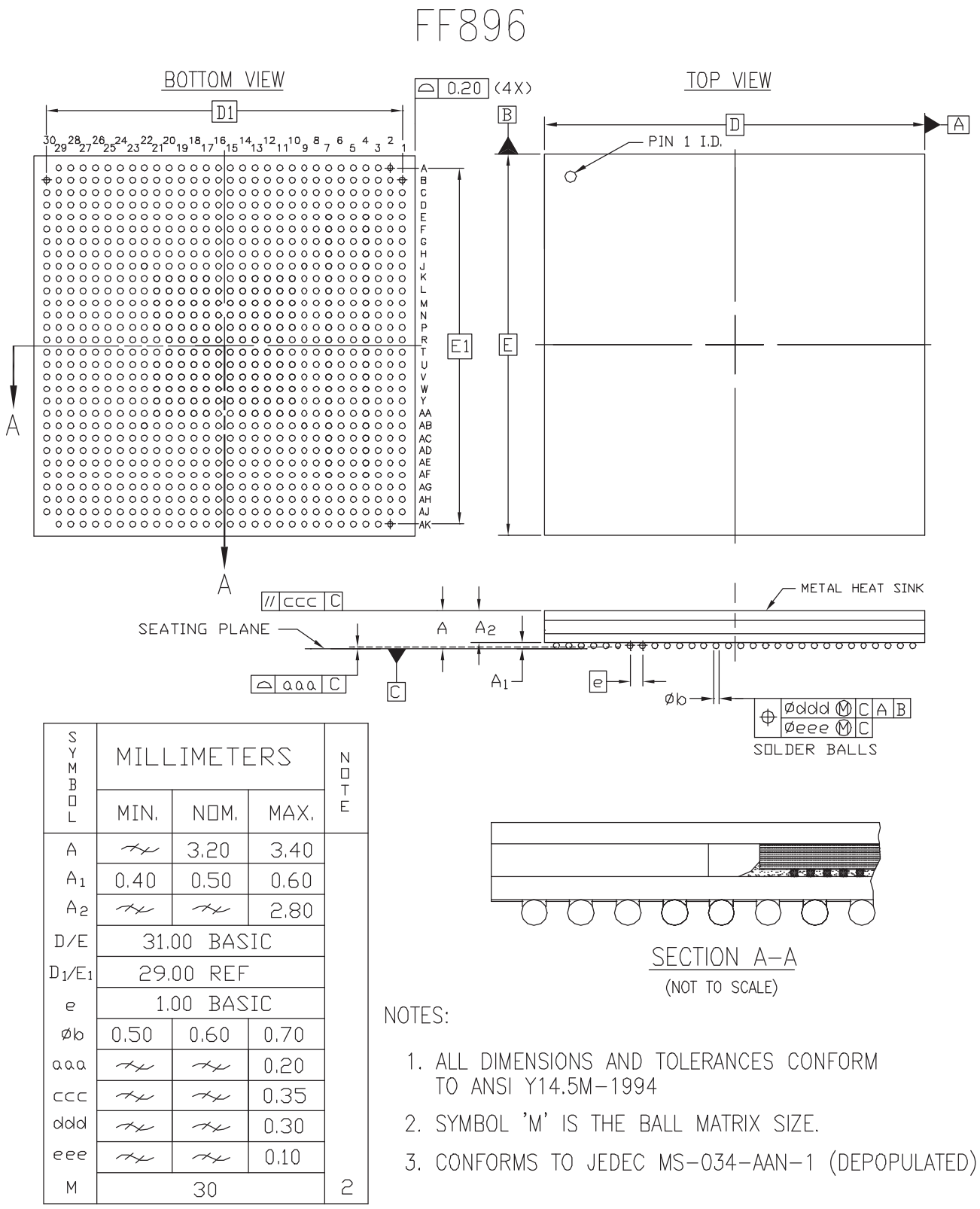
Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
1	VCCO_1		K13			
1	VCCO_1		K12			
1	VCCO_1		K11			
1	VCCO_1		K10			
1	VCCO_1		J13			
1	VCCO_1		J12			
1	VCCO_1		J11			
1	VCCO_1		J10			
2	VCCO_2		R10			
2	VCCO_2		P10			
2	VCCO_2		N10			
2	VCCO_2		N9			
2	VCCO_2		M10			
2	VCCO_2		M9			
2	VCCO_2		L10			
2	VCCO_2		L9			
2	VCCO_2		K9			
2	VCCO_2		J9			
3	VCCO_3		AB9			
3	VCCO_3		AA9			
3	VCCO_3		Y10			
3	VCCO_3		Y9			
3	VCCO_3		W10			
3	VCCO_3		W9			
3	VCCO_3		V10			
3	VCCO_3		V9			
3	VCCO_3		U10			
3	VCCO_3		T10			
4	VCCO_4		AB13			
4	VCCO_4		AB12			
4	VCCO_4		AB11			
4	VCCO_4		AB10			
4	VCCO_4		AA15			
4	VCCO_4		AA14			
4	VCCO_4		AA13			
4	VCCO_4		AA12			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
N/A	GND		N17			
N/A	GND		N16			
N/A	GND		N15			
N/A	GND		N14			
N/A	GND		N13			
N/A	GND		N12			
N/A	GND		M19			
N/A	GND		M18			
N/A	GND		M17			
N/A	GND		M16			
N/A	GND		M15			
N/A	GND		M14			
N/A	GND		M13			
N/A	GND		M12			
N/A	GND		L28			
N/A	GND		L25			
N/A	GND		L20			
N/A	GND		L11			
N/A	GND		L6			
N/A	GND		L3			
N/A	GND		H30			
N/A	GND		H1			
N/A	GND		F25			
N/A	GND		F18			
N/A	GND		F13			
N/A	GND		F6			
N/A	GND		E26			
N/A	GND		E5			
N/A	GND		D27			
N/A	GND		D22			
N/A	GND		D19			
N/A	GND		D12			
N/A	GND		D9			
N/A	GND		D4			
N/A	GND		C28			
N/A	GND		C17			

FF896 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A		3.20	3.40	
A_1	0.40	0.50	0.60	
A_2			2.80	
D/E	31.00 BASIC			
D_1/E_1	29.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa			0.20	
ccc			0.35	
ddd			0.30	
eee			0.10	
M	30			2

NOTES:

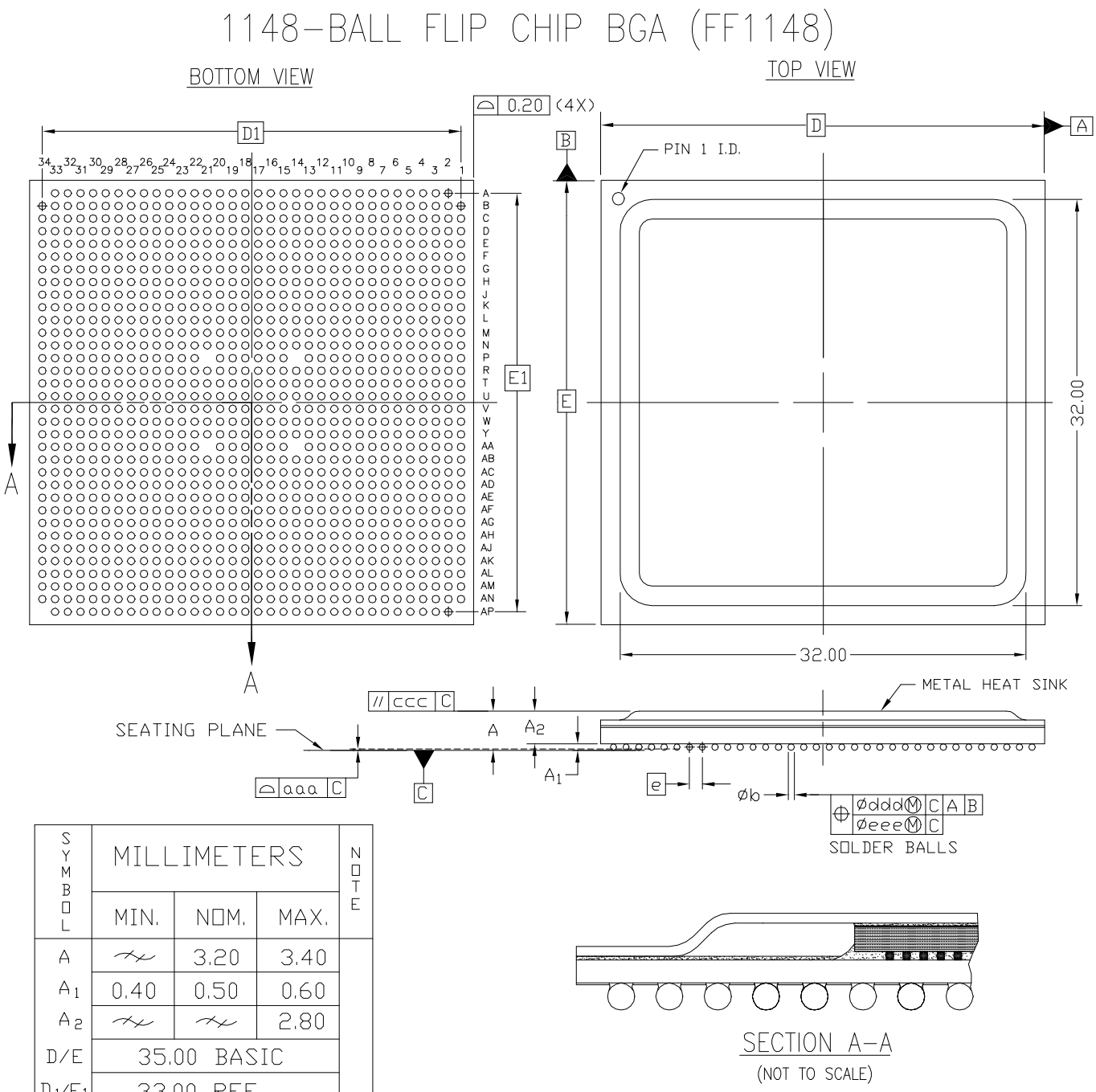
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS–034–AAN–1 (DEPOPULATED)

Figure 5: **FF896 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L02P_2	D9		
2	IO_L03N_2	B7		
2	IO_L03P_2	A7		
2	IO_L04N_2/VREF_2	B6		
2	IO_L04P_2	A6		
2	IO_L05N_2	E8		
2	IO_L05P_2	D8		
2	IO_L06N_2	B4		
2	IO_L06P_2	A4		
2	IO_L07N_2	B3		
2	IO_L07P_2	A3		
2	IO_L08N_2	H7		
2	IO_L08P_2	H8		
2	IO_L09N_2	C6		
2	IO_L09P_2	C7		
2	IO_L10N_2/VREF_2	C5		
2	IO_L10P_2	B5		
2	IO_L11N_2	K8		
2	IO_L11P_2	J8		
2	IO_L12N_2	C1		
2	IO_L12P_2	C2		
2	IO_L13N_2	E7		
2	IO_L13P_2	D7		
2	IO_L14N_2	J6		
2	IO_L14P_2	J7		
2	IO_L15N_2	D5		
2	IO_L15P_2	D6		
2	IO_L16N_2/VREF_2	E4		
2	IO_L16P_2	D4		
2	IO_L17N_2	L9		
2	IO_L17P_2	K9		
2	IO_L18N_2	E3		
2	IO_L18P_2	D3		
2	IO_L19N_2	D1		
2	IO_L19P_2	D2		
2	IO_L20N_2	K7		
2	IO_L20P_2	L7		
2	IO_L21N_2	F6		

FF1148 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	---	3.20	3.40	
A_1	0.40	0.50	0.60	
A_2	---	---	2.80	
D/E	35.00 BASIC			
D_1/E_1	33.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa	---	---	0.20	
ccc	---	---	0.35	
ddd	---	---	0.30	
eee	---	---	0.10	
M	34			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAR-1 (DEPOPULATED)

Figure 7: **FF1148 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	VCCAUX		AM11		
N/A	VCCAUX		AN33		
N/A	VCCAUX		AN10		
N/A	VCCAUX		AV39		
N/A	VCCAUX		AV4		
N/A	VCCAUX		AW38		
N/A	VCCAUX		AW22		
N/A	VCCAUX		AW21		
N/A	VCCAUX		AW5		
N/A	VCCAUX		AA42		
N/A	VCCAUX		AA41		
N/A	VCCAUX		AA2		
N/A	VCCAUX		AA1		
N/A	VCCAUX		Y42		
N/A	VCCAUX		Y1		
N/A	VCCAUX		L32		
N/A	VCCAUX		L11		
N/A	VCCAUX		K33		
N/A	VCCAUX		K10		
N/A	VCCAUX		E39		
N/A	VCCAUX		E4		
N/A	VCCAUX		D38		
N/A	VCCAUX		D22		
N/A	VCCAUX		D21		
N/A	VCCAUX		D5		
N/A	GND		AB38		
N/A	GND		AB35		
N/A	GND		AB32		
N/A	GND		AB26		
N/A	GND		AB25		
N/A	GND		AB24		
N/A	GND		AB23		
N/A	GND		AB22		
N/A	GND		AB21		
N/A	GND		AB20		
N/A	GND		AB19		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
6	IO_L15P_6	AP39	
6	IO_L15N_6/VREF_6	AP40	
6	IO_L16P_6	AP36	
6	IO_L16N_6	AP37	
6	IO_L17P_6	AH31	
6	IO_L17N_6	AG31	
6	IO_L18P_6	AN41	
6	IO_L18N_6	AN42	
6	IO_L19P_6	AN40	
6	IO_L19N_6	AM40	
6	IO_L20P_6	AG34	
6	IO_L20N_6	AG35	
6	IO_L21P_6	AN37	
6	IO_L21N_6/VREF_6	AN38	
6	IO_L22P_6	AN36	
6	IO_L22N_6	AM36	
6	IO_L23P_6	AG32	
6	IO_L23N_6	AG33	
6	IO_L24P_6	AM41	
6	IO_L24N_6	AM42	
6	IO_L25P_6	AM38	
6	IO_L25N_6	AM39	
6	IO_L26P_6	AF35	
6	IO_L26N_6	AF36	
6	IO_L27P_6	AM37	
6	IO_L27N_6/VREF_6	AL36	
6	IO_L28P_6	AL41	
6	IO_L28N_6	AK41	
6	IO_L29P_6	AF32	
6	IO_L29N_6	AF33	
6	IO_L30P_6	AL39	
6	IO_L30N_6	AL40	
6	IO_L31P_6	AL37	
6	IO_L31N_6	AL38	
6	IO_L32P_6	AF31	
6	IO_L32N_6	AE31	
6	IO_L33P_6	AK39	